

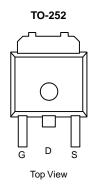
P-Channel 30 V (D-S) MOSFET

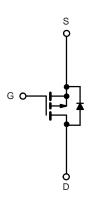
PRODUCT SUMMARY				
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a		
- 30	$0.005 \text{ at V}_{GS} = -10 \text{ V}$	-100		
- 30	0.007 at V _{GS} = - 4.5 V	-90		

FEATURES

• Compliant to RoHS Directive 2002/95/EC







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit V			
Gate-Source Voltage	V_{GS}	± 20				
Continuous Drain Current (T _{.1} = 175 °C)	T _C = 25 °C	1	- 100 ^a	^		
Continuous Diam Current (1) = 175 C)	T _C = 125 °C	I _D	- 90			
Pulsed Drain Current	I _{DM}	- 280	Α			
Avalanche Current	I _{AR}	- 80				
Repetitive Avalanche Energy ^b	L = 0.1 mH	E _{AR}	180	mJ		
Dawer Dissination	T _C = 25 °C (TO-220AB and TO-263)	Б	187 ^d	W		
Power Dissipation	T _A = 25 °C (TO-263) ^c	P _D	3.75			
Operating Junction and Storage Temperature Range		T _J , T _{sta}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Limit	Unit		
Junction-to-Ambient	PCB Mount (TO-263) ^c	В	40	°C/W		
Junction-to-Ambient	Free Air (TO-220AB)	R _{thJA}	62.5			
Junction-to-Case		R _{thJC}	0.8	1		

Notes:

- a. Package limited.
- b. Duty cycle \leq 1 %.
- c. When mounted on 1" square PCB (FR-4 material).
- d. See SOA curve for voltage derating.

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.



www.VBsemi.com

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 30				
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	- 1		- 3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		V _{DS} = - 30 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 125 °C			- 50	μΑ	
		V _{DS} = - 30 V, V _{GS} = 0 V, T _J = 175 °C			- 250		
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 120			Α	
		V _{GS} = - 10 V, I _D = - 30 A		0.005			
Drain-Source On-State Resistance ^a	ь	V _{GS} = - 10 V, I _D = - 30 A, T _J = 125 °C		0.006			
Diani-Source On-State Resistance	R _{DS(on)}	V _{GS} = - 10 V, I _D = - 30 A, T _J = 175 °C		0.008		Ω	
		V _{GS} = - 4.5 V, I _D = - 20 A		0.007			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 75 A	20			S	
Dynamic ^b							
Input Capacitance	C _{iss}			8000		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = -25 \text{ V}, f = 1 \text{ MHz}$		1565			
Reversen Transfer Capacitance	C _{rss}			715			
Total Gate Charge ^c	Qg			160	240		
Gate-Source Charge ^c	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 10 V, I _D = - 75 A		32		nC	
Gate-Drain Charge ^c	Q_{gd}]		30		1	
Turn-On Delay Time ^c	t _{d(on)}			25	40		
Rise Time ^c	t _r	$V_{DD} = -15 \text{ V}, R_{L} = 0.2 \Omega$		225	360	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong -75 \text{ A}, V_{GEN} = -10 \text{ V}, R_g = 2.5 \Omega$		150	240		
Fall Time ^c	t _f]		210	340		
Source-Drain Diode Ratings and Cha	racteristics ^b	(T _C = 25 °C)					
Continuous Current	I _S				- 80	A	
Pulsed Current	I _{SM}				- 240		
Forward Voltage ^a	V _{SD}	I _F = -75 A, V _{GS} = 0 V	V _{GS} = 0 V		- 1.5	V	
Reverse Recovery Time	t _{rr}			55	100	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 75 A, dl/dt = 100 A/μs		2.5	5	Α	
Reverse Recovery Charge	Q _{rr}			0.07	0.25	μC	

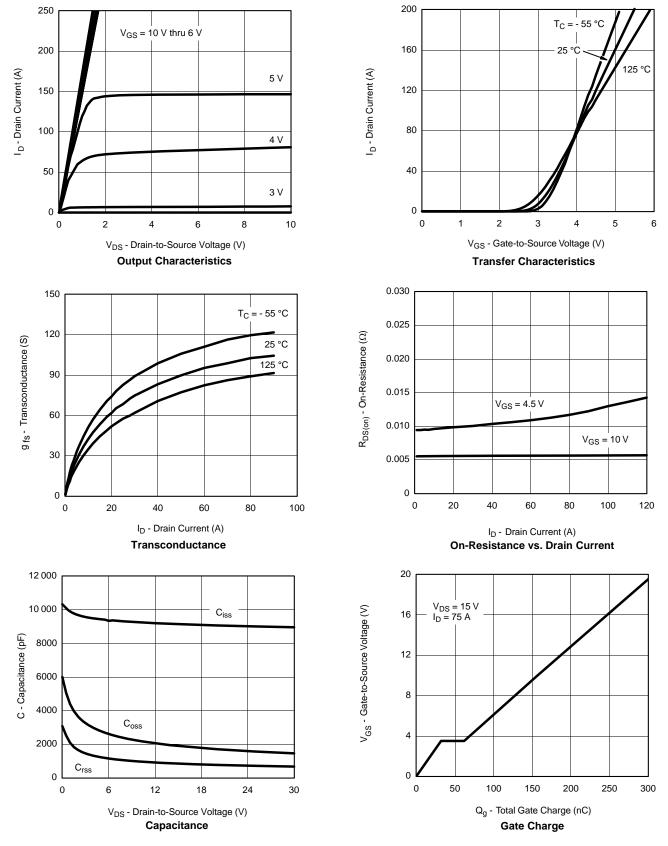
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

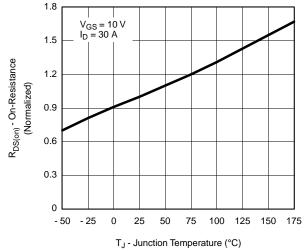


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

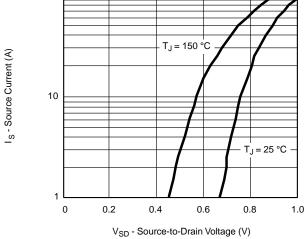




TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

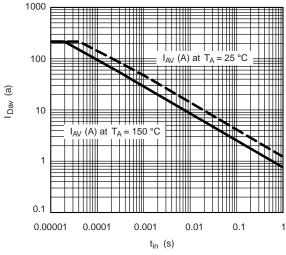


On-Resistance vs. Junction Temperature

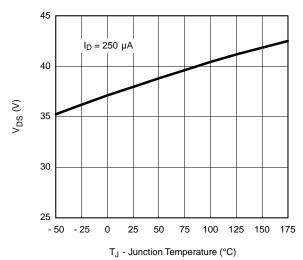


100

Source-Drain Diode Forward Voltage



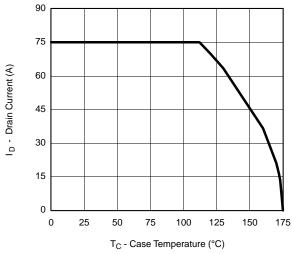
Avalanche Current vs. Time

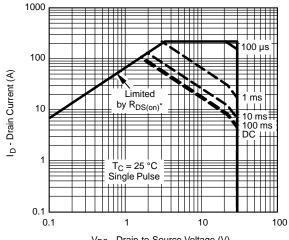


Drain Source Breakdown vs. Junction Temperature

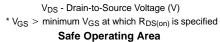


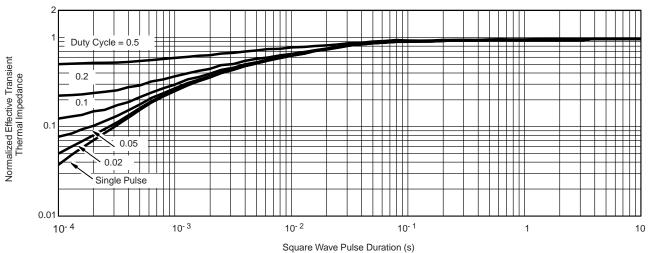
THERMAL RATINGS





Maximum Avalanche and Drain Current vs. Case Temperature





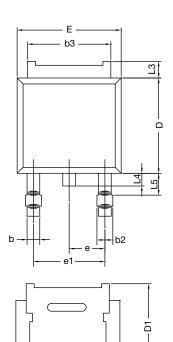
Normalized Thermal Transient Impedance, Junction-to-Case

服务热线:400-655-8788

5

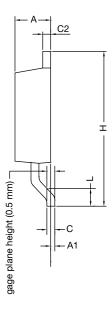


TO-252AA CASE OUTLINE



E1

6



	MILLIMETERS		INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
А	2.18	2.38	0.086	0.094	
A1	-	0.127	-	0.005	
b	0.64	0.88	0.025	0.035	
b2	0.76	1.14	0.030	0.045	
b3	4.95	5.46	0.195	0.215	
С	0.46	0.61	0.018	0.024	
C2	0.46	0.89	0.018	0.035	
D	5.97	6.22	0.235	0.245	
D1	5.21	-	0.205	-	
E	6.35	6.73	0.250	0.265	
E1	4.32	-	0.170	-	
Н	9.40	10.41	0.370	0.410	
е	2.28	BSC	0.090 BSC		
e1	4.56	4.56 BSC		BSC	
L	1.40	1.78	0.055	0.070	
L3	0.89	1.27	0.035	0.050	
L4	-	1.02	-	0.040	
L5	1.14	1.52	0.045	0.060	
ECN: X12-0247-Rev. M. 24-Dec-12					

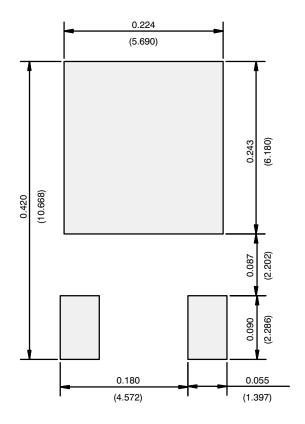
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347

Note

• Dimension L3 is for reference only.



RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads Dimensions in Inches/(mm)

服务热线:400-655-8788

7



Disclaimer

All products due to improve reliability, function or design or for other reasons, product specifications and data are subject to change without notice.

Taiwan VBsemi Electronics Co., Ltd., branches, agents, employees, and all persons acting on its or their representatives (collectively, the "Taiwan VBsemi"), assumes no responsibility for any errors, inaccuracies or incomplete data contained in the table or any other any disclosure of any information related to the product.(www.VBsemi.com)

Taiwan VBsemi makes no guarantee, representation or warranty on the product for any particular purpose of any goods or continuous production. To the maximum extent permitted by applicable law on Taiwan VBsemi relinquished: (1) any application and all liability arising out of or use of any products; (2) any and all liability, including but not limited to special, consequential damages or incidental; (3) any and all implied warranties, including a particular purpose, non-infringement and merchantability guarantee.

Statement on certain types of applications are based on knowledge of the product is often used in a typical application of the general product VBsemi Taiwan demand that the Taiwan VBsemi of. Statement on whether the product is suitable for a particular application is non-binding. It is the customer's responsibility to verify specific product features in the products described in the specification is appropriate for use in a particular application. Parameter data sheets and technical specifications can be provided may vary depending on the application and performance over time. All operating parameters, including typical parameters must be made by customer's technical experts validated for each customer application. Product specifications do not expand or modify Taiwan VBsemi purchasing terms and conditions, including but not limited to warranty herein.

Unless expressly stated in writing, Taiwan VBsemi products are not intended for use in medical, life saving, or life sustaining applications or any other application. Wherein VBsemi product failure could lead to personal injury or death, use or sale of products used in Taiwan VBsemi such applications using client did not express their own risk. Contact your authorized Taiwan VBsemi people who are related to product design applications and other terms and conditions in writing.

The information provided in this document and the company's products without a license, express or implied, by estoppel or otherwise, to any intellectual property rights granted to the VBsemi act or document. Product names and trademarks referred to herein are trademarks of their respective representatives will be all.

Material Category Policy

Taiwan VBsemi Electronics Co., Ltd., hereby certify that all of the products are determined to be RoHS compliant and meets the definition of restrictions under Directive of the European Parliament 2011/65 / EU, 2011 Nian. 6. 8 Ri Yue restrict the use of certain hazardous substances in electrical and electronic equipment (EEE) - modification, unless otherwise specified as inconsistent.(www.VBsemi.com)

Please note that some documents may still refer to Taiwan VBsemi RoHS Directive 2002/95 / EC. We confirm that all products identified as consistent with the Directive 2002/95 / EC European Directive 2011/65 /.

Taiwan VBsemi Electronics Co., Ltd. hereby certify that all of its products comply identified as halogen-free halogen-free standards required by the JEDEC JS709A. Please note that some Taiwanese VBsemi documents still refer to the definition of IEC 61249-2-21, and we are sure that all products conform to confirm compliance with IEC 61249-2-21 standard level JS709A.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by VBsemi Elec manufacturer:

Other Similar products are found below:

IRFD120 JANTX2N5237 BUK455-60A/B MIC4420CM-TR VN1206L NDP4060 SI4482DY IPS70R2K0CEAKMA1 SQD23N06-31L-GE3
TK16J60W,S1VQ(O 2SK2614(TE16L1,Q) DMN1017UCP3-7 DMN1053UCP4-7 SQJ469EP-T1-GE3 NTE2384 DMC2700UDMQ-7
DMN2080UCB4-7 DMN61D9UWQ-13 US6M2GTR DMN31D5UDJ-7 DMP22D4UFO-7B DMN1006UCA6-7 DMN16M9UCA6-7
STF5N65M6 IRF40H233XTMA1 STU5N65M6 DMN6022SSD-13 DMN13M9UCA6-7 DMTH10H4M6SPS-13 DMN2990UFB-7B
IPB80P04P405ATMA2 2N7002W-G MCAC30N06Y-TP MCQ7328-TP NTMC083NP10M5L BXP7N65D BXP4N65F AOL1454G
WMJ80N60C4 BXP2N20L BXP2N65D BXT1150N10J BXT1700P06M TSM60NB380CP ROG RQ7L055BGTCR DMNH15H110SK3-13
SLF10N65ABV2 BSO203SP BSO211P IPA60R230P6